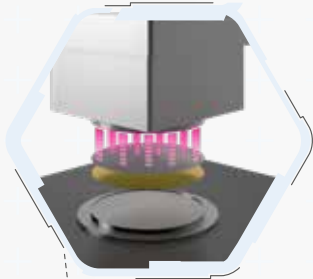
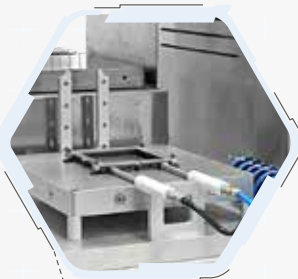
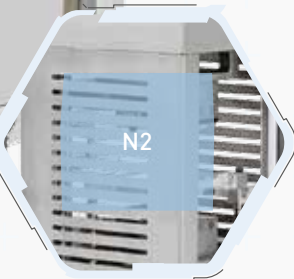


AMX X-SINTER P50 SERIES

PRESSURE
Uniform Pressure and Quality Control System.



WAFER PROCESS
Wafer to wafer sintering and wafer Lamination.



INERT ATMOSPHERE
N2, Vacuum, forming gas or other on request

R&D, SEMI AUTO SOLUTIONS P54 - P55

A larger tool allows to pressure sinter dies on single substrate, as entire mastercard or frame. It is possible to modulate the clamping stroke to pressure sinter thicker components like already molded packages on pin-thin heatsink.

P54 and P55 have a wide range of forces and are able to provide best accuracy both with low and high force. Thanks to the wafer level tool it is also possible to process entire wafers up to 12"Ø.

Temperature and pressure profile curves can be easily exported by FTP server or USB.



EASY TO USE INTERFACE
Multi-language interface, traceability of pressure and temperature profiles and USB full data export.

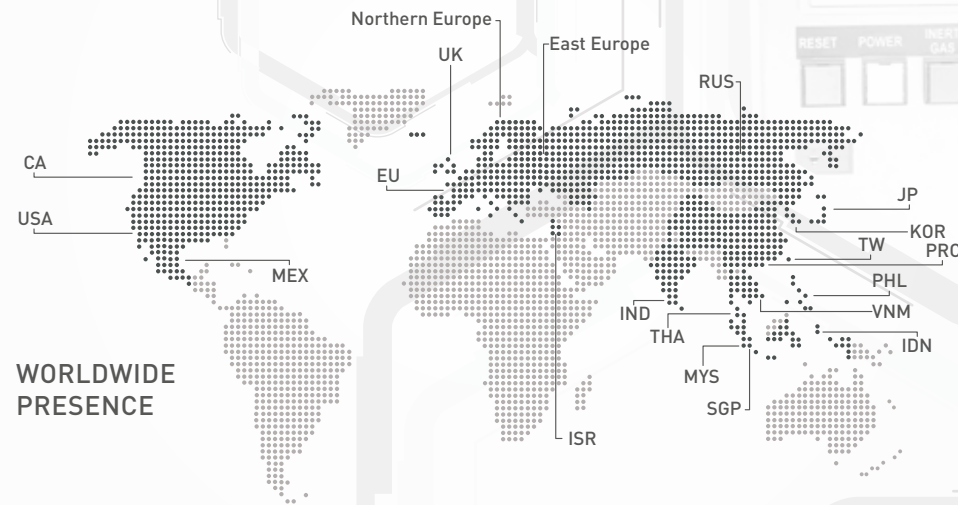


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WORLDWIDE PRESENCE



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X-SINTER P50 SERIES



POWER ELECTRONIC EQUIPMENT

04/2022 Rev 02 - ENG

R&D, MANUAL SOLUTIONS P51 - P52 - P53

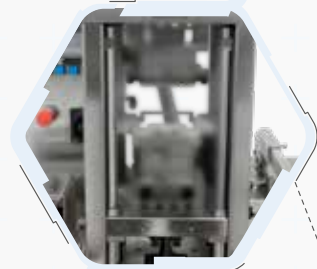
X Sinter P50 Series is a complete range of manual sintering presses suitable for R&D, prototyping and quality inspections.

Designed for Lab and clean room environment, it is the perfect solution for the first approach to the silver or copper sintering process.

X Sinter P50 Series is a completely manual press available in different configurations and able to reach the same sintering pressure and temperature of the inline one.

Key advantages are: high accuracy and reliability.

It is really flexible and has lot of possible options in order to adapt to the specific customer's needs.



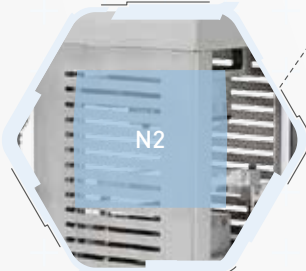
PRESSURE
Uniform Pressure and Quality Control System.



PROOF-OF-CONCEPT
Available for Testing at AMX Plant Facility.



MANUAL SOLUTION
Easy to use for low volume production, trials and R&D operations



INERT ATMOSPHERE
N2, Vacuum, forming gas or other on request

MANUAL SOLUTIONS

SEMI AUTO SOLUTIONS



P51



P52



P53



P54



P55

SINTERING AREA	75 x 75 mm	110 x 110 mm	140 x 140 mm	200 x 200 mm	300 x 300 mm
MAX CLAMPING FORCE	16 kN	39 kN	62 kN	100 kN	100 or 300 kN
MAX SINTERING PRESSURE	40 MPa	40 MPa	40 MPa	40 MPa	40 MPa
AMX FORCE SENSOR	Available: Continuous monitoring system for quality control	Available: Continuous monitoring system for quality control	Available: Continuous monitoring system for quality control	Available: Continuous monitoring system for quality control	Available: Continuous monitoring system for quality control
CONTROLLED ATMOSPHERE	N2, Vacuum, Forming gas other on request	N2, Vacuum, Forming gas other on request	N2, Vacuum, Forming gas other on request	N2, Vacuum, Forming gas other on request	N2, Vacuum, Forming gas other on request
SINTERING TOOL	Flat plate customizable with fixture	Flat plate customizable with fixture	Flat plate customizable with fixture	Flat plate customizable with fixture	Flat plate customizable with fixture
WAFER PROCESS	-	-	-	-	Wafer lamination and Wafer sintering
MAX TEMP. (BOTH SIDE)	350°C	350°C	350°C	350°C	350°C
PRE-HEATING AREA	up to 250°C	up to 250°C	up to 250°C	up to 250°C	up to 250°C
POST-COOLING AREA	Natural cooling	Natural cooling	Natural cooling	Cooling circuit	Cooling circuit
EXT. THERMOCOUPLE CONNECTION	up to 2	up to 2	up to 4	up to 4	up to 4
INTERFACE	AMX multilanguage easy interface	AMX multilanguage easy interface	AMX multilanguage easy interface	AMX multilanguage easy interface and USB data export	AMX multilanguage easy interface and USB data export
TRACEABILITY	-	-	-	Database, DMC scanner available	Database, DMC scanner available
DIMENSIONS	W600 x D650 x H1200 mm	W750 x D800 x H1400 mm	W800 x D900 x H1400 mm	W1000 x D1000 x H1750 mm	W1300 x D1300 x H1750 mm
WEIGHT	150 Kg	225 Kg	450 Kg	1290 Kg	1590 Kg